

- Up to 4 ARM® Cortex<sup>™</sup>- A53 Processor
- Two ARM Cortex<sup>™</sup>- R5 Real-time Processors
- ARM Mali<sup>™</sup>- 400 Graphic Processing Unit
- Platform Management Unit for Power and Safety Management
- Config and Security Unit
- Programmable Logic with High Speed Tranceivers
- H264 / H265 video codec
- DDR4 memory on board up to 64bits bandwith
- Pinout matching with BORA product line
- Designed for industrial environment
- CG/EG/EV support from ZU2 to ZU5 families

## ONDA

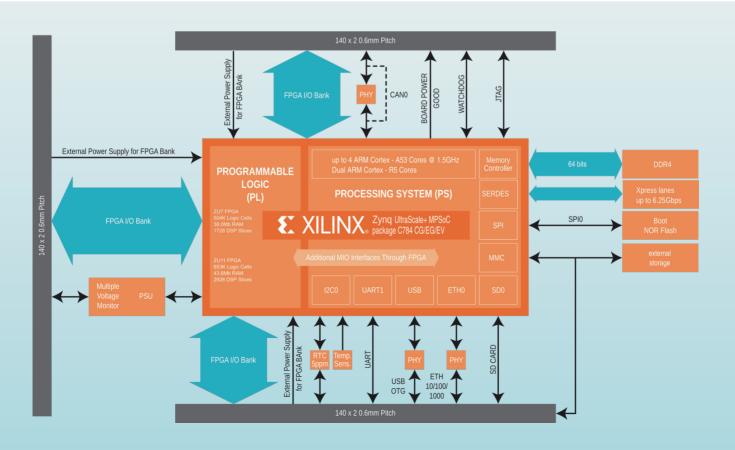
XILINX ZYNQ UltraScale+ MPSoC SYSTEM ON MODULE



In the new era of Internet Of Things, customers are requiring to add connectivity and new functionalities on their products. Customers are also keen to product longevity and hardware/software maintenance. For these reasons DAVE Embedded Systems has designed a new solution based on Xilinx Zynq® UltraScale+<sup>™</sup> MPSoC devices that is compatible with the existing BORA System On Module based on Xilinx Zynq® MPSoC.

Xilinx Zynq® UltraScale+<sup>™</sup> MPSoC devices provide 64-bit processor scalability while combining real-time control with soft and hard engines for graphics, video, waveform, and packet processing. Built on a common real-time processor and programmable logic equipped platform, three distinct variants include dual application processor (CG) devices, quad application processor and GPU (EG) devices, and video codec (EV) devices, creating unlimited possibilities for applications and Industrial Internet-of-Things. Zynq UltraScale+ MPSoC provide up to 5X systemlevel performance-per-watt compared to the Zynq-7000 SoC family. Zynq UltraScale+ devices combine a high-performance ARM-based multicore, multiprocessing system with ASIC-class programmable logic. Dual- and quad-core application processor equipped devices deliver maximum scalability, and are capable of offloading critical applications, such as graphics and video pipelining, to dedicated processing blocks, along with a full complement of integrated peripherals and connectivity cores suitable for next-generation systems. For the most compute intensive processing tasks, integrated programmable logic offers up to 100X performance improvement over processor-based implementations. Dramatic power savings are achieved through fine-grained control of power domains and gated power islands. With specialized processing elements for different workloads, Zynq UltraScale+ MPSoCs integrate the right engines for the right tasks for next-generation embedded challenges.

With this design, DAVE Embedded Systems priovides its customers with a platform that benefits of the latest Xilinx technology together with the compatibility with the existing SoM product line. Business continuity and product maintenance are the key words around this product including high reliability options like conformal coating, sealing and lead process manufacturing for avionic and defense applications.



**ULTRA LINE** 

RMATION	CPU	up to 4 ARM Cortex-A53 ZYNQ @ up to 1.5GHz Two ARM Cortex - R5 Cores SOC package: C784, supported devices: ZU2-3-4-5CG, ZU2-3-4-5EG,ZU4-5EV			
	Co-Processor	Only on EV devices: ARM Mali-400 MP2 Graphics Processing Unit Video Codec Unit for H264/265 4K video streams			
	Supervisor	On-board power supply supervision and power sequencer Watchdog and RTC			
	Memory SDRAM	DDR4 technology @ 64bits, TBD supported sizes			
	NOR	Bootable SPI NOR, TBD supported sizes			
	External Storages	TBD (NAND SLC or eMMC)			
	nterfaces (full-spec models) *				
	LAN	Fast Ethernet 10/100/1000 Mbps Additional RMII interface			
	UART	up to 2x UART ports			
	USB	up to 2 x 2.0 OTG ports			
	CAN	up to 2 x CAN			
	Debug	JTAG IEEE 1149.1 Test Access Port			
	Other PFPGA Model Logic Cells	TBD SD/SDIO 2.0/MMC 3.31 compliant controllers up to TBD x I2C channels up to TBD x SPI channels GPIO available			
С Ц	FPGA				
N	Model	ZU2 FPGA	ZU3 FPGA	ZU4 FPGA	ZU5 FPGA
		10010			
Υ Π	Logic Cells	103K	154K	192K	256K
<b>IINAR</b>	RAM	5.3Mb	7.6Mb	4.5Mb	5.1Mb
I IMINARY	RAM DSP Slices	5.3Mb 240	7.6Mb 360	4.5Mb 728	
BFI IMINA	RAM DSP Slices Tranceivers	5.3Mb 240 TBD - max b	7.6Mb 360 andwidth 6.250	4.5Mb 728	5.1Mb
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade	5.3Mb 240	7.6Mb 360 andwidth 6.250	4.5Mb 728	5.1Mb
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical	5.3Mb 240 TBD - max b -1, -2L, -2, -3	7.6Mb 360 andwidth 6.250 3, -1M	4.5Mb 728	5.1Mb
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch	4.5Mb 728 Gbps each	5.1Mb 1056
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres	7.6Mb 360 andwidth 6.250 3, -1M D.6mm pitch temptative to be ss but overall s	4.5Mb 728 Gbps each e footprint com ize should be b	5.1Mb 1056 patible with bigger
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra	5.1Mb 1056 patible with bigger ade.
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial	7.6Mb 360 andwidth 6.250 3, -1M D.6mm pitch temptative to be ss but overall s	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra	5.1Mb 1056 patible with bigger ade.
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial Cooling syst	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1	7.6Mb 360 andwidth 6.250 3, -1M D.6mm pitch temptative to be ss but overall s , Industrial - up em required (d	4.5Mb 728 Gbps each e footprint com ize should be to to defense gra epends on des conformal coa	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73	4.5Mb 728 Gbps each e footprint com ize should be to to defense gra epends on des conformal coa	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin 0 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1 Support for 5	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des conformal coa aded process	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process PSU	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1 Support for 3 3.3V, on-boa	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to b ss but overall s , Industrial - up em required (d Humiseal 1B73 Sealing and Le	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des conformal coa aded process ulation	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process PSU Input	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1 Support for 3 3.3V, on-boa	7.6Mb 360 andwidth 6.250 3, -1M D.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73 Sealing and Le ard voltage reg	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des conformal coa aded process ulation	5.1Mb 1056 patible with bigger tide. ign)
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process PSU Input FPGA banks	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for I Support for I Support for S 3.3V, on-boa PSU can be	7.6Mb 360 andwidth 6.250 3, -1M D.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73 Sealing and Le ard voltage reg	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des conformal coa aded process ulation nally	5.1Mb 1056 patible with bigger ude. ign) tting
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process PSU Input FPGA banks Software	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1 Support for 1 Support for 2 3.3V, on-boa PSU can be	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73 Sealing and Le ard voltage regi provided exter	4.5Mb 728 Gbps each e footprint com ize should be b to defense gra epends on des conformal coa aded process ulation nally K Works bootlo	5.1Mb 1056 patible with bigger ade. ign) tting
BFI IMINA	RAM DSP Slices Tranceivers Speed Grade Mechanical Connectors Size Temperature Coating Process PSU Input FPGA banks Software Bootloader	5.3Mb 240 TBD - max b -1, -2L, -2, -3 3 x 140 pin ( 90x55mm - 1 BORA Xpres Commercial Cooling syst Support for 1 Support for 1 Support for 3 3.3V, on-boa PSU can be U-Boot, TBE Linux 4.x.x a	7.6Mb 360 andwidth 6.250 3, -1M 0.6mm pitch temptative to be ss but overall s , Industrial - up em required (d Humiseal 1B73 Sealing and Le ard voltage reg provided exter	4.5Mb 728 Gbps each e footprint com ize should be k to defense gra epends on des conformal coa aded process ulation nally K Works bootlo D support for o	5.1Mb 1056 patible with bigger ade. bign) tting ader ther O.S.

The ONDA evaluation kit will be available as a development platform that includes a SOM, a carrier board which permits to test part of board capabilities.

\*: interface availability depends on pin multiplease contact your local FAE.



## Product code configurator \*

Family Processor NOR flash DDR4 RAM Storage TBD TBD DND

ORDERING INFORMATION NOT YET AVAILABLE

The availability of part numbers depends on effective availlability of Xilinx part numbers



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